# CY74FCT2652T 8-BIT REGISTERED TRANSCEIVER WITH 3-STATE OUTPUTS

Q PACKAGE (TOP VIEW)

CPAB [

SAB 1 2

GAB 3

A<sub>1</sub> [] 4

 $A_2 \coprod 5$ 

 $A_3 \square 6$ 

A<sub>4</sub> [] 7

A<sub>5</sub> [ 8

A<sub>6</sub> [ 9

A<sub>7</sub> 🛮 10

A<sub>8</sub> L 11

GND [] 12

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24 🛮 V<sub>CC</sub>

22 SBA

21 GBA

20 B<sub>1</sub>

19 B<sub>2</sub>

18 B<sub>3</sub>

17 🛮 B<sub>4</sub>

16 🛮 B<sub>5</sub>

15 B<sub>6</sub>

14 B<sub>7</sub>

13 B<sub>8</sub>

23 CPBA

- Function and Pinout Compatible With FCT and F Logic
- 25-Ω Output Series Resistors Reduce Transmission-Line Reflection Noise
- Reduced V<sub>OH</sub> (Typically = 3.3 V) Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- Matched Rise and Fall Times
- Fully Compatible With TTL Input and Output Logic Levels
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)
- 12-mA Output Sink Current
  15-mA Output Source Current
- Independent Register for A and B Buses
- Multiplexed Real-Time and Stored Data Transfer
- 3-State Outputs

#### description

The CY74FCT2652T consists of bus transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal storage registers. Control (GAB and GBA) inputs control the transceiver functions. Select-control (SAB and SBA) inputs select either real-time or stored data transfer.

The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during transition between stored and real-time data. A low input level selects real-time data, and a high level selects stored data. Data on the A or B data bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock (CPAB or CPBA) inputs, regardless of levels at the select- or enable-control inputs. When SAB and SBA are in the real-time transfer mode, it also is possible to store data without using the internal D-type flip-flops by simultaneously enabling GAB and GBA. In this configuration, each output reinforces its input. Thus, when all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last state.

On-chip termination resistors at the outputs reduce system noise caused by reflections. The CY74FCT2652T can replace the CY74FCT652T to reduce noise in existing designs.

This device is fully specified for partial-power-down applications using I<sub>off</sub>. The I<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



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#### **ORDERING INFORMATION**

TA	PACKAGET		SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
-40°C to 85°C	QSOP – Q	Tape and reel	5.4	CY74FCT2652CTQCT	FCT2652C	
	QSOP - Q	Tape and reel	6.3	CY74FCT2652ATQCT	FCT2652A	

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

#### **FUNCTION TABLE**

INPUTS			DAT	A I/O	OPERATION OR FUNCTION			
GAB	GBA	CPAB	СРВА	SAB	SBA	A <sub>1</sub> -A <sub>8</sub>	B <sub>1</sub> -B <sub>8</sub>	OPERATION OR FUNCTION
L	Н	H or L	H or L	Χ	Х	Input	Input	Isolation
L	Н	<b>↑</b>	1	Χ	Х	Input	Input	Store A and B data
Х	Н	<b>↑</b>	H or L	Х	Х	Input	Unspecified§	Store A data, hold B data
Н	Н	<b>↑</b>	1	χ‡	Х	Input	Output	Store A data in both registers
L	Х	H or L	1	Х	Х	Unspecified§	Input	Hold A data, store B data
L	L	$\uparrow$	1	Χ	χ‡	Output	Input	Store B data in both registers
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	Χ	Н	Output	Input	Stored B data to A bus
Н	Н	Х	Х	L	Χ	Input	Output	Real-time A data to B bus
Н	Н	H or L	Χ	Н	Χ	Input	Output	Stored A data to B bus
Н	L	H or L	H or L	Н	Н	Output	Output	Stored A data to B bus and stored B data to A bus

H = High logic level, L = Low logic level, X = Don't care, ↑ = Low-to-high clock transition



<sup>‡</sup> Select control = L: clocks can occur simultaneously.

Select control = H: clocks must be staggered in order to load both registers.

<sup>§</sup> The data output functions can be enabled or disabled by various signals at GAB or GBA. Data input functions always are enabled, i.e., data at the bus pins is stored on every low-to-high transition of the clock inputs.

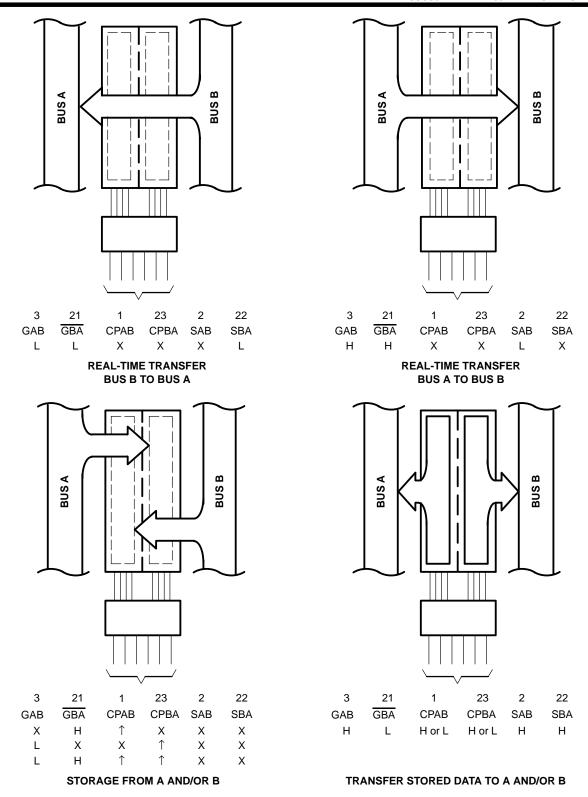
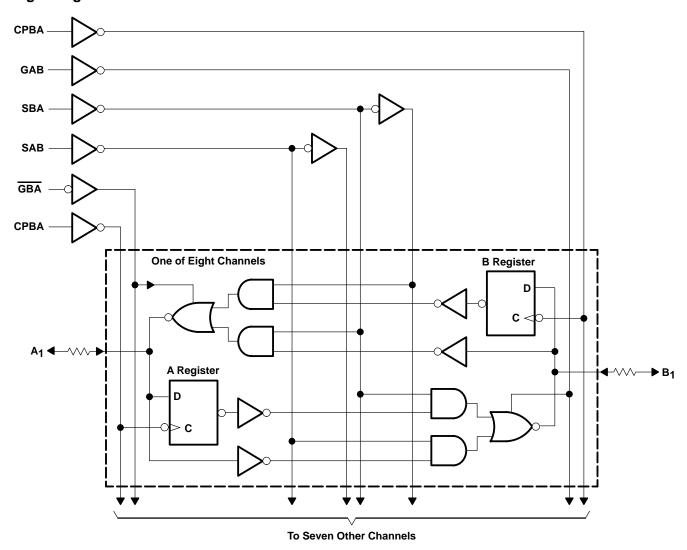


Figure 1. Bus-Management Functions



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### logic diagram



# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range to ground potential	–0.5 V to 7 V
DC input voltage range	–0.5 V to 7 V
DC output voltage range	–0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 1)	
Ambient temperature range with power applied, T <sub>A</sub>	. −65°C to 135°C
Storage temperature range, T <sub>stg</sub>	. −65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.



# recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.75	5	5.25	V
VIH	High-level input voltage	2			V
V <sub>IL</sub>	Low-level input voltage			0.8	V
IOH	High-level output current			-15	mA
loL	Low-level output current			12	mA
TA	Operating free-air temperature	-40		85	°C

NOTE 2: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation.

# CY74FCT2652T 8-BIT REGISTERED TRANSCEIVER WITH 3-STATE OUTPUTS

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
VIK	$V_{CC} = 4.75,$	$I_{IN} = -18 \text{ mA}$			-0.7	-1.2	V
Voн	$V_{CC} = 4.75,$	$I_{OH} = -15 \text{ mA}$		2.4	3.3		V
V <sub>OL</sub>	$V_{CC} = 4.75,$	$I_{OL}$ = 12 mA			0.3	0.55	V
R <sub>out</sub>	$V_{CC} = 4.75,$	$I_{OL}$ = 12 mA		20	25	40	Ω
V <sub>hys</sub>	All inputs				0.2		V
lį	$V_{CC} = 5.25 \text{ V},$	$V_{IN} = V_{CC}$				5	μΑ
lіН	$V_{CC} = 5.25 \text{ V},$	$V_{IN} = 2.7 \text{ V}$				±1	μΑ
I <sub>IL</sub>	$V_{CC} = 5.25 \text{ V},$	$V_{IN} = 0.5 V$				±1	μΑ
lozh	$V_{CC} = 5.25 \text{ V},$	V <sub>OUT</sub> = 2.7 V				10	μΑ
lozL	$V_{CC} = 5.25 \text{ V},$	V <sub>OUT</sub> = 0.5 V				-10	μΑ
los <sup>‡</sup>	$V_{CC} = 5.25 \text{ V},$	VOUT = 0 V		-60	-120	-225	mA
l <sub>off</sub>	$V_{CC} = 0 V$ ,	V <sub>OUT</sub> = 4.5 V				±1	μΑ
Icc	V <sub>CC</sub> = 5.25 V,	$V_{IN} \le 0.2 V$	$V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.1	0.2	mA
ΔlCC	$V_{CC} = 5.25 \text{ V}, V_{IN} = 3.4$	$V$ , $f_1 = 0$ , Outputs ope	n		0.5	2	mA
I <sub>CCD</sub> ¶	$V_{CC} = \underline{5.25} \text{ V}$ , One inpu GAB = $\overline{\text{GBA}}$ = GND, $V_{IN}$				0.06	0.12	mA/ MHz
	V <sub>CC</sub> = 5.25 V,	One bit switching at f <sub>1</sub> = 5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.7	1.4	
1-#	Outputs open, GAB = GBA = GND,	at 50% duty cycle	V <sub>IN</sub> = 3.4 V or GND		1.2	3.4	^
lC <sub>#</sub>	SAB = GBA = GND, SAB = CPAB = GND, SBA = VCC	Eight bits switching at f <sub>1</sub> = 5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		2.8	5.6	mA
		at 50% duty cycle	V <sub>IN</sub> = 3.4 V or GND		5.1	14.6	
C <sub>i</sub>					5	10	pF
Co					9	12	pF

<sup>†</sup> Typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

# I<sub>C</sub> = I<sub>CC</sub> +  $\Delta$ I<sub>CC</sub> × D<sub>H</sub> × N<sub>T</sub> + I<sub>CCD</sub> (f<sub>0</sub>/2 + f<sub>1</sub> × N<sub>1</sub>) Where:

I<sub>C</sub> = Total supply current

I<sub>CC</sub> = Power-supply current with CMOS input levels

 $\Delta I_{CC}$  = Power-supply current for a TTL high input ( $V_{IN} = 3.4 \text{ V}$ )

D<sub>H</sub> = Duty cycle for TTL inputs high N<sub>T</sub> = Number of TTL inputs at D<sub>H</sub>

I<sub>CCD</sub> = Dynamic current caused by an input transition pair (HLH or LHL)

= Clock frequency for registered devices, otherwise zero

f<sub>1</sub> = Input signal frequency

 $N_1$  = Number of inputs changing at  $f_1$ 

All currents are in milliamperes and all frequencies are in megahertz.

Values for these conditions are examples of the I<sub>CC</sub> formula.



Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, Ins tests should be performed last.

<sup>§</sup> Per TTL-driven input (VIN = 3.4 V); all other inputs at VCC or GND

This parameter is derived for use in total power-supply calculations.

# timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

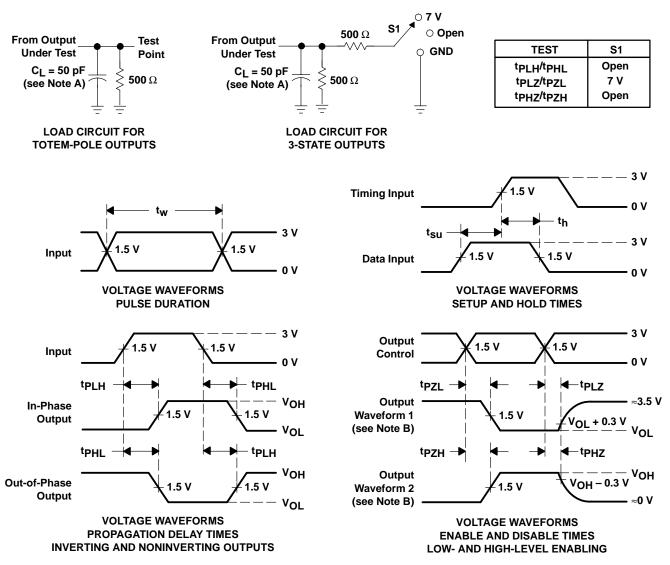
				2652AT	CY74FCT2652CT		UNIT
		MIN	MAX	MIN	MAX	UNII	
tw†	Pulse duration, clock		2		2		ns
t <sub>su</sub>	Setup time, before clock↑	A or B	1.5		1.5		ns
th	Hold time, after clock↑	A or B	5		5		ns

<sup>†</sup> With one data channel switching,  $t_{W(L)} = t_{W(H)} = 4$  ns and  $t_r = t_f = 1$  ns.

### switching characteristics over operating free-air temperature range (see Figure 2)

PARAMETER	FROM	то	CY74FCT2652AT		CY74FCT2652CT		UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	UNII
t <sub>PLH</sub>	A or B	B or A	1.5	6.3	1.5	5.4	ns
<sup>t</sup> PHL	AOIB	BOIA	1.5	6.3	1.5	5.4	115
<sup>t</sup> PZH	GAB or GBA	B or A	1.5	9.8	1.5	7.8	ns
t <sub>PZL</sub>	GAD OF GDA	B 01 A	1.5	9.8	1.5	7.8	115
<sup>t</sup> PHZ	GAB or GBA	B or A	1.5	6.3	1.5	6.3	ns
t <sub>PLZ</sub>	GAD OF GDA	BOLA	1.5	6.3	1.5	6.3	115
<sup>t</sup> PLH	CPAB or CPBA	B or A	1.5	6.3	1.5	5.7	ns
<sup>t</sup> PHL	CPAB OI CPBA	B OF A	1.5	6.3	1.5	5.7	115
t <sub>PLH</sub>	SAB or SBA	B or A	1.5	7.7	1.5	6.2	ns
<sup>t</sup> PHL	SAB OF SBA	BULK	1.5	7.7	1.5	6.2	115

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms



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